

ABSTRACT

A component mounting apparatus is provided with a board holding device for holding a board at a board holding position, a first mounting head for holding and taking out a component fed from a first component feeding position and mounting the component on the board held at the board holding position, a second mounting head for holding and taking out the component fed from a second component feeding position and mounting the component on the held board, and a component feeding device having a wafer holding table for holding a wafer on which the respective components are fed so that the wafer holding table can be moved reciprocationally between the first component feeding position and the second component feeding position.